

N AND P-CHANNEL ENHANCEMENT MODE POWER MOSFET N 加 P 沟道增强型 MOS 管

**N-CH  $V_{DS}= 40V$**

**$R_{DS(ON)}, V_{GS}@10V, I_{DS}@6.0A = 31m\Omega$**

**$R_{DS(ON)}, V_{GS}@4.5V, I_{DS}@5.0A = 45m\Omega$**

**P-CH  $V_{DS}= -40V$**

**$R_{DS(ON)}, V_{GS}@-10V, I_{DS}@-5.0A = 45m\Omega$**

**$R_{DS(ON)}, V_{GS}@-4.5V, I_{DS}@-4.0A = 63m\Omega$**

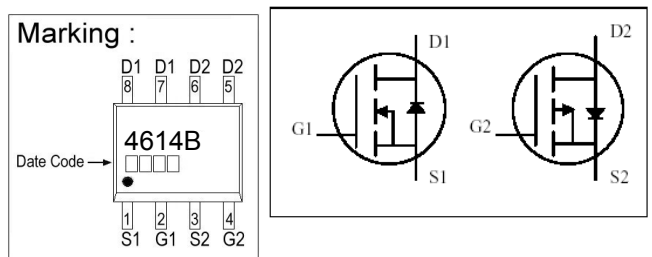
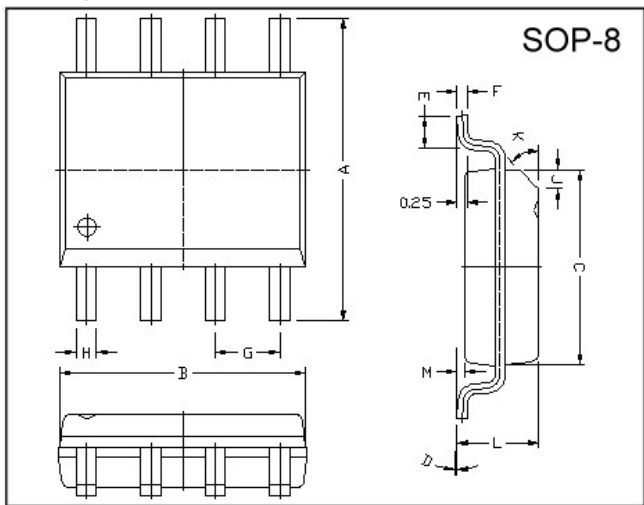
**Features 特性**

Advanced trench process technology 高级的加工技术

High Density Cell Design For Ultra Low On-Resistance 极低的导通电阻高密度的单元设计

Improved Shoot-Through FOM 改良的成形工艺

**Package Dimensions 封装尺寸及外形图**



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.80	6.20	M	0.10	0.25
B	4.80	5.00	H	0.35	0.49
C	3.80	4.00	L	1.35	1.75
D	0°	8°	J	0.375 REF.	
E	0.40	0.90	K	45°	
F	0.19	0.25	G	1.27 TYP.	

**Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted) 25°C 极限参数和热特性**

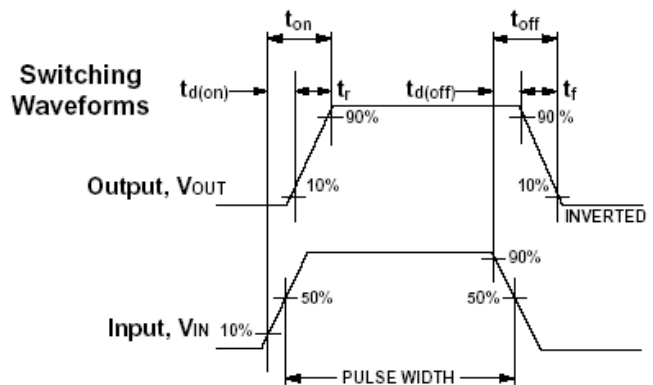
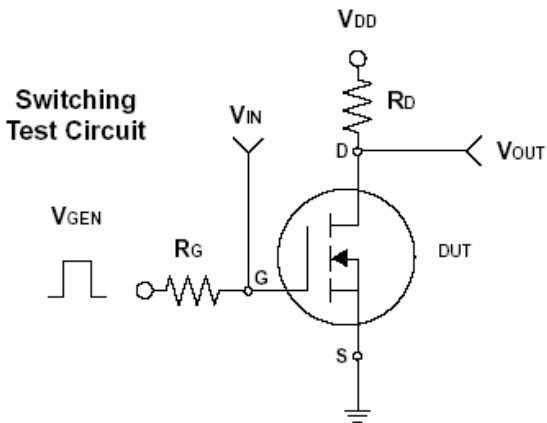
Parameter 极限参数	Symbol 符号	Ratings 等级		Unit 单位
		N-沟道	P-沟道	
Drain-Source Voltage 漏源电压	$V_{DS}$	40	-40	V
Gate-Source Voltage 栅源电压	$V_{GS}$	±20	±20	V
Continuous Drain Current 连续漏极电流	$I_D @TA=25^\circ C$	6.0	-5.0	A
Continuous Drain Current 连续漏极电流	$I_D @TA=70^\circ C$	5.0	-4.0	A
Pulsed Drain Current 脉冲漏极电流	$I_{DM}$	20	-20	A
Total Power Dissipation 功耗	$P_D @TA=25^\circ C$	2.1		W
Linear Derating Factor 线性因子		0.016		W/°C
Operating Junction and Storage Temperature Range 使用及储存温度	$T_j, T_{stg}$	-55 ~ +150		°C

N-Channel Electrical Characteristics (T<sub>j</sub> = 25°C unless otherwise specified)

N 沟道电气特性 25°C

Parameter 参数	符号	Test Condition 测试条件	最小值	典型值	最大值	单位
<b>Static 静态参数</b>						
Drain-Source Breakdown Voltage 漏源击穿电压	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	40			V
Drain-Source On-State Resistance 漏源导通电阻	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5.0A		33.0	45.0	mΩ
Drain-Source On-State Resistance 漏源导通电阻	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6.0A		23.0	31.0	
Gate Threshold Voltage 开启电压	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA	1	1.8	3	V
Zero Gate Voltage Drain Current 零栅压漏极电流	I <sub>DSS</sub>	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V			1	µA
Gate Body Leakage 漏极短路时截止栅电流	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20V, V <sub>DS</sub> = 0V			± 100	nA
Forward Transconductance 正向跨导	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5A		17	—	S
<b>Dynamic 动态参数</b>						
Total Gate Charge 栅极总电荷	Q <sub>g</sub>	V <sub>DS</sub> = 20V, I <sub>D</sub> = 1.5A V <sub>GS</sub> = 10V		14.5		nC
Gate-Source Charge 栅-源极电荷	Q <sub>gs</sub>			1.5		
Gate-Drain Charge 栅-漏极电荷	Q <sub>gd</sub>			3.5		
Turn-On Delay Time 导通延迟时间	t <sub>d(on)</sub>	V <sub>DD</sub> = 20V, R <sub>L</sub> = 5 Ω I <sub>D</sub> = 1A, V <sub>GEN</sub> = 10V R <sub>G</sub> = 3 Ω		10.5		ns
Turn-On Rise Time 导通上升时间	t <sub>r</sub>			16.05		
Turn-Off Delay Time 关断延迟时间	t <sub>d(off)</sub>			39		
Turn-Off Fall Time 关断下降时间	t <sub>f</sub>			10		
Input Capacitance 输入电容	C <sub>iss</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V f = 1.0 MHz		745		pF
Output Capacitance 输出电容	C <sub>oss</sub>			65.7		
Reverse Transfer Capacitance 反向传输电容	C <sub>rss</sub>			53.35		
<b>Source-Drain Diode 源漏二极管参数</b>						
Max. Diode Forward Current 最大正向电流	I <sub>S</sub>				4.3	A
Diode Forward Voltage 正向电压	V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V			1.3	V

Note: Pulse test: pulse width ≤ 300µs, duty cycle ≤ 2% 注意: 脉冲测试: 脉冲宽度 ≤ 300µs 死区 ≤ 2%



N-Channel Characteristics Curve N 沟道电气性能特征曲线

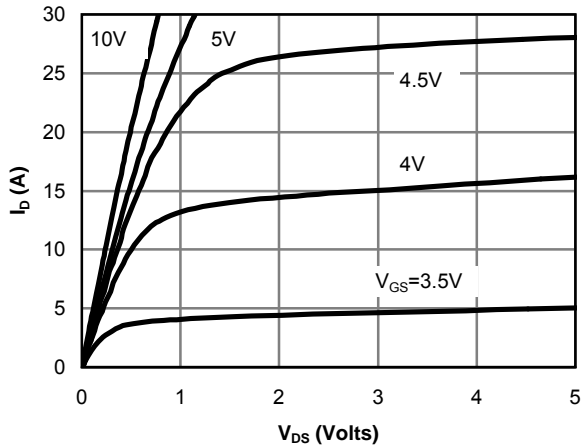


Figure 1: On-Region Characteristics

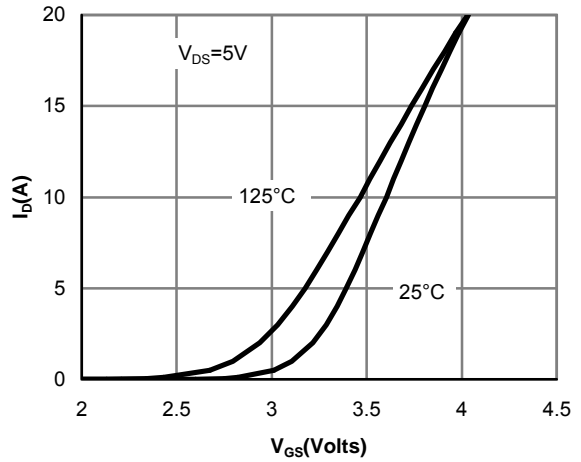


Figure 2: Transfer Characteristics

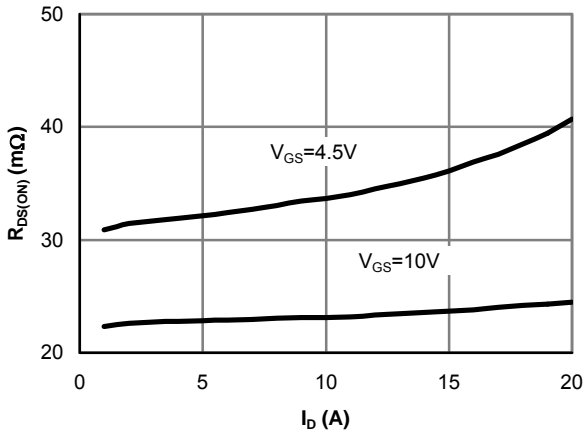


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

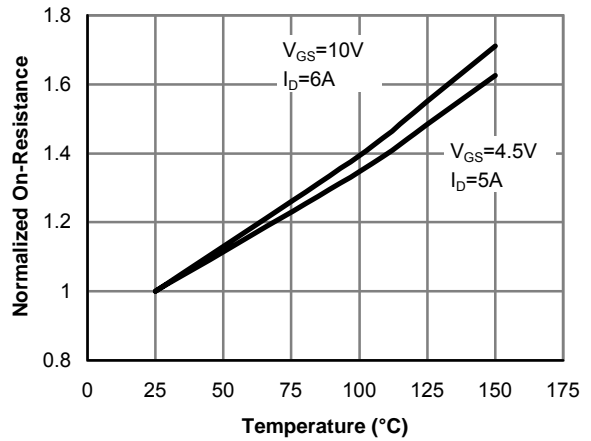


Figure 4: On-Resistance vs. Junction Temperature

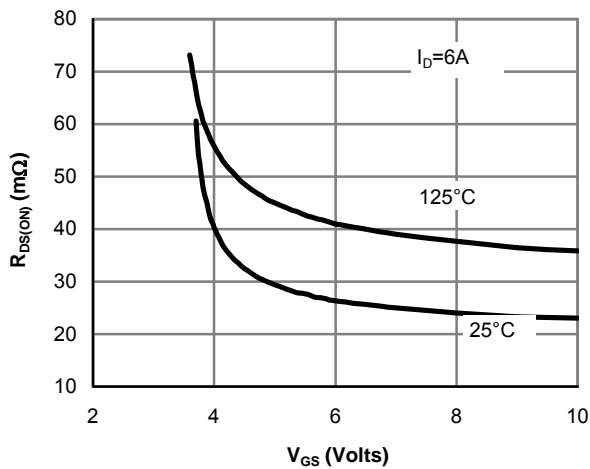


Figure 5: On-Resistance vs. Gate-Source Voltage

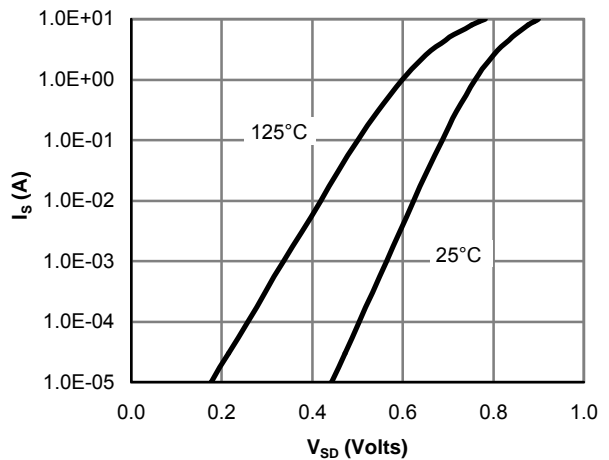


Figure 6: Body-Diode Characteristics

P-Channel Electrical Characteristics (T<sub>j</sub> = 25°C unless otherwise specified) P 沟道电气特性 25°C

Parameter 参数	符号	Test Condition 测试条件	最小值	典型值	最大值	单位
<b>Static 静态参数</b>						
Drain-Source Breakdown Voltage 漏源击穿电压	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250µA	-40			V
Drain-Source On-State Resistance 漏源导通电阻	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4.0A		51	63	mΩ
Drain-Source On-State Resistance 漏源导通电阻	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -5.0A		35	45	
Gate Threshold Voltage 栅源电压	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250µA	-1	-1.7	-3	V
Zero Gate Voltage Drain Current 0 栅压漏极电流	I <sub>DSS</sub>	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V			-1	µA
Gate Body Leakage 漏极短路时截止栅电流	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Forward Transconductance 正向跨导	g <sub>fs</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -5A		5		S
<b>Dynamic<sup>3)</sup> 动态参数</b>						
Total Gate Charge 栅极总电荷	Q <sub>g</sub>	V <sub>DS</sub> = -20V, I <sub>D</sub> = -1.5A V <sub>GS</sub> = -10V		21.52		nC
Gate-Source Charge 栅-源极电荷	Q <sub>gs</sub>			2.4		
Gate-Drain Charge 栅-漏极电荷	Q <sub>gd</sub>			4.82		
Turn-On Delay Time 导通延迟时间	t <sub>d(on)</sub>	V <sub>DD</sub> = -20V, R <sub>L</sub> = 5Ω I <sub>D</sub> = -1A, V <sub>GEN</sub> = -10V R <sub>G</sub> = 3Ω		15.08		ns
Turn-On Rise Time 导通上升时间	t <sub>r</sub>			14.53		
Turn-Off Delay Time 关断延迟时间	t <sub>d(off)</sub>			51		
Turn-Off Fall Time 关断下降时间	t <sub>f</sub>			14.8		
Input Capacitance 输入电容	C <sub>iss</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V f = 1.0 MHz		1238		pF
Output Capacitance 输出电容	C <sub>oss</sub>			99		
Reverse Transfer Capacitance 反向传输电容	C <sub>rss</sub>			67.5		
<b>Source-Drain Diode 源漏二极管参数</b>						
Max. Diode Forward Current 最大正向电流	I <sub>S</sub>				-2.3	A
Diode Forward Voltage 正向电压	V <sub>SD</sub>	I <sub>S</sub> = -2.3A, V <sub>GS</sub> = 0V			-1.2	V

## P-Channel

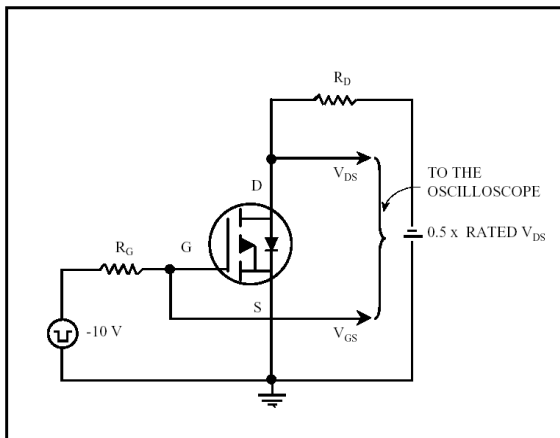


Fig 13. Switching Time Circuit

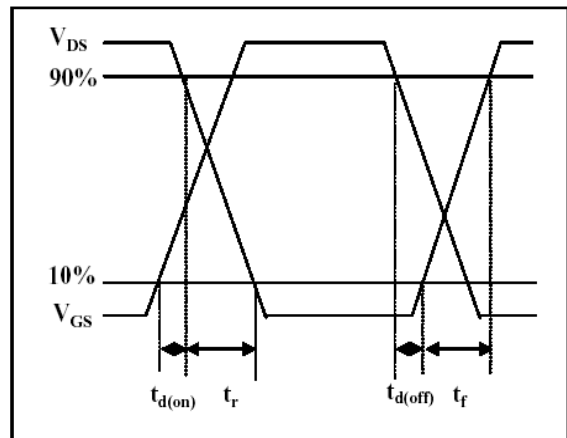


Fig 14. Switching Time Waveform

**P-Channel Characteristics Curve P 沟道电气性能特征曲线**

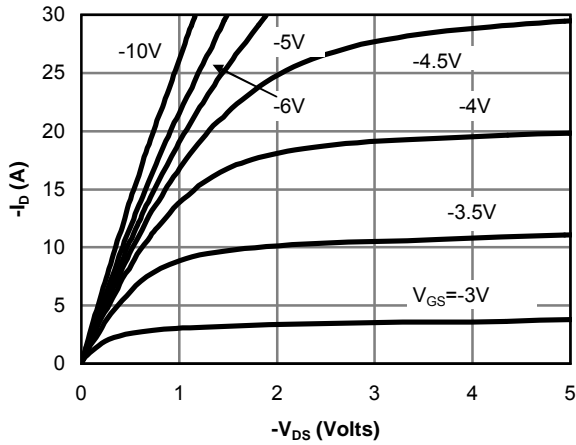


Figure 1: On-Region Characteristics

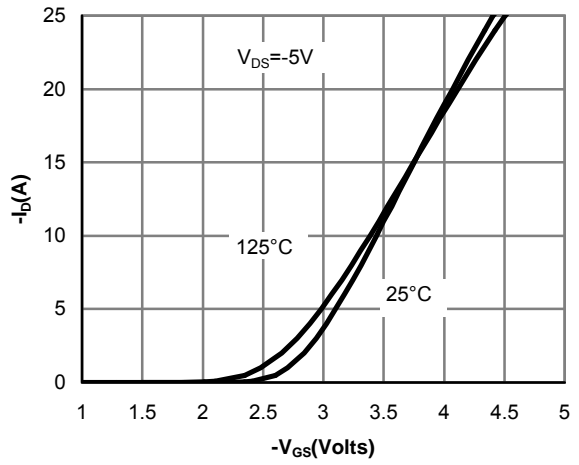


Figure 2: Transfer Characteristics

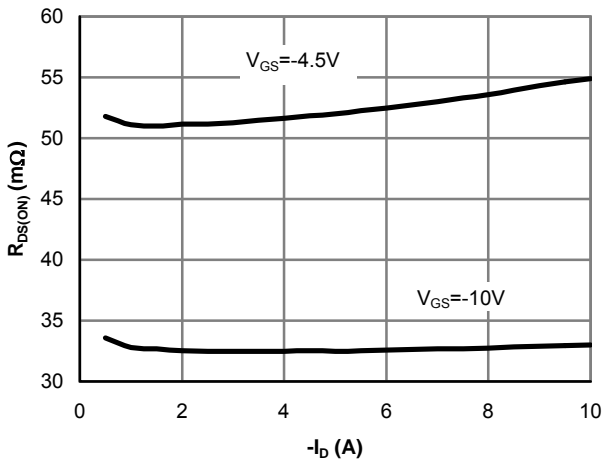


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

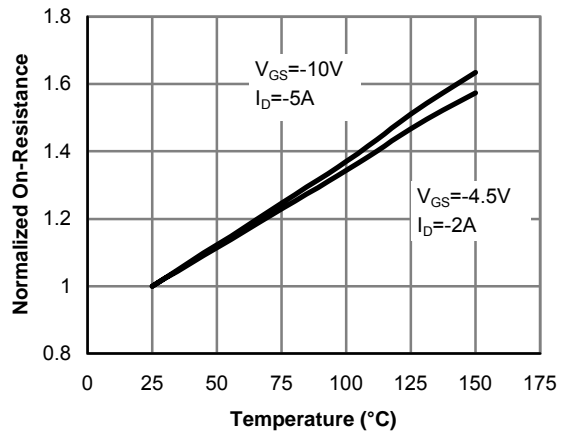


Figure 4: On-Resistance vs. Junction Temperature

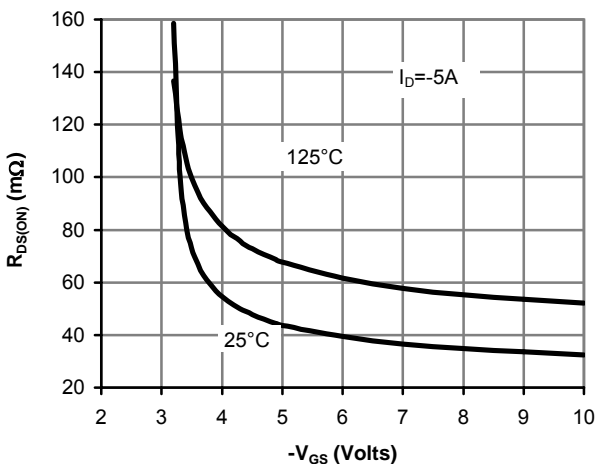


Figure 5: On-Resistance vs. Gate-Source Voltage

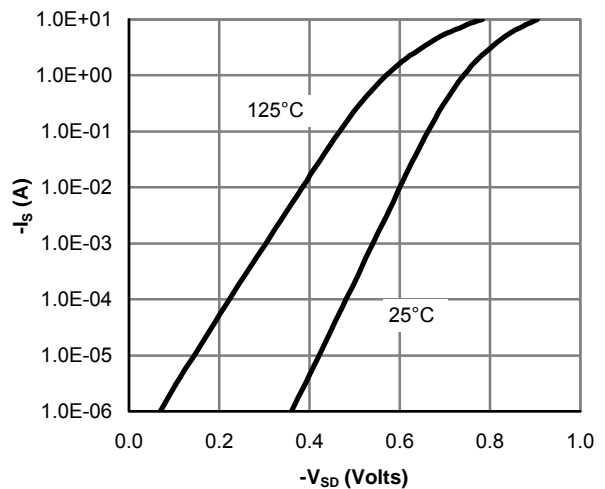


Figure 6: Body-Diode Characteristics